

Semiconductor Device Type:	EMC	LDFN-4L-7.0x5.0x1.6mm-NiAu	-							
Semiconductor Device Type.	EIVIC	"Contained In"	% Total					1		
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	22.19	(mg) Total	Kovar	% of Total Weight	15.8
Nickel	7440-02-0	Kovar	4.58	6.44	45813		Nickel	7440-02-0	29.00	
Cobalt	7440-48-4	Kovar	2.69	3.77	26856		Cobalt	7440-48-4	17.00	
Iron	7439-89-6	Kovar	8.46	11.88	84611		Iron	7439-89-6	53.56	
Carbon	7440-44-0	Kovar	0.00	0.00	32		Carbon	7440-44-0	0.02	
Silicon	7440-21-3	Kovar	0.00	0.00	32		Silicon	7440-21-3	0.02	
Manganese	7439-96-5	Kovar	0.06	0.09	632		Manganese	7439-96-5	0.40	
Nickel	7440-02-0	Nickel Plating	0.86	1.21	8614			Total	100.00	
Aluminum Oxide	1344-28-1	Ceramics	54.92	77.14	549163					
Silicon Oxide	7631-86-9	Ceramics	3.66	5.14	36611	1.21	(mg) Total	Nickel Plating	% of Total Weight	0.8
Chromium oxide	1308-38-9	Ceramics	1.22	1.71	12204		Nickel	7440-02-0	100.00	
Molybdenum	7439-98-7	Ceramics	1.22	1.71	12204			Total	100.00	
Iron	7439-89-6	Kovar Seal Sing	4.41	6.20	44106					
Nickel	7440-02-0	Kovar Seal Sing	2.51	3.52	25080	85.71	(mg) Total	Ceramics	% of Total Weight	61.
Cobalt	7440-48-4	Kovar Seal Sing	1.56	2.19	15567		Aluminum Oxide	1344-28-1	90.00	
Trade Secret	Trade Secret	Kovar Seal Sing	0.17	0.24	1730		Silicon Oxide	7631-86-9	6.00	
Gold	7440-57-5	Plate	0.48	0.67	4805		Chromium oxide	1308-38-9	2.00	
Nickel	7440-02-0	Plate	0.32	0.45	3203		Molybdenum	7439-98-7	2.00	
Tungsten	7440-33-7	Metalizing	6.34	8.91	63420			Total	100.00	
Trade Secret	Trade Secret	Metalizing	0.06	0.09	641					
Silver	7440-22-4	Solder	2.27	3.19	22742	12.15	(mg) Total	Kovar Seal Sing	% of Total Weight	8.0
Copper	7440-50-8	Solder	0.93	1.30	9289		Iron	7439-89-6	51.00	
Silicon	7440-21-3	Integrated Circuit	0.25	0.35	2469		Nickel	7440-02-0	29.00	
Aluminum	7429-90-5	Integrated Circuit	0.00	0.00	10		Cobalt	7440-48-4	18.00	
Titanium	7440-32-6	Integrated Circuit	0.00	0.00	7		Trade Secret	Trade Secret	2.00	
Tungsten	7440-33-7	Integrated Circuit	0.00	0.00	5			Total	100.00	
Copper	7440-50-8	Integrated Circuit	0.00	0.00	0					
Arsenic	7440-38-2	Integrated Circuit	0.00	0.00	0	1.12	(mg) Total	Plate	% of Total Weight	0.8
Boron	7440-42-8	Integrated Circuit	0.00	0.00	0		Gold	7440-57-5	0.00	
Fluorine	7782-41-4	Integrated Circuit	0.00	0.00	0		Nickel	7440-02-0	100.00	
Phosphorus	7723-14-0	Integrated Circuit	0.00	0.00	0			Total	100.00	
Silver	7440-22-4	Adhesive	0.23	0.32	2285					
Epoxy Resin	Trade Secret	Adhesive	0.05	0.06	457	9.00	(mg) Total	Metalizing	% of Total Weight	6.
Epoxy Resin Modifier	Trade Secret	Adhesive	0.03	0.04	305		Tungsten	7440-33-7	99.00	
Gold	7440-57-5	Gold Wire	0.43	0.60	4271		Trade Secret	Trade Secret	1.00	
Quartz	14808-60-7	Blank	1.04	1.46	10394			Total	100.00	
Silver	7440-22-4	Internal Electrode	0.01	0.01	77					
Chromium	7440-47-3	Internal Electrode	0.00	0.00	9	4.50	(mg) Total	Solder	% of Total Weight	3.
Silver	7440-22-4	Conductive Adhesive	0.97	1.37	9729	4.50	Silver	7440-22-4	71.00	
Silicon Oxide	Trade Secret	Conductive Adhesive	0.13	0.18	1315		Copper	7440-50-8	29.00	
	Trade Secret	Conductive Adhesive	0.13	0.10	1315		Сорреі	Total	100.00	
	11440 000101									
Silicone Resin		TOTALS							100.00	
	140.47	TOTALS		140.47	1,000,000	0.35	(ma) Total	Integrated Circuit		0.
	140.47	mg Iotal Mass				0.35	(mg) Total	Integrated Circuit	% of Total Weight	0.:
Silicone Resin		mg Total Mass	100.00	140.47	1,000,000	0.35	Silicon	7440-21-3	% of Total Weight 99.10	0.:
Silicone Resin		mg Total Mass	100.00	140.47	1,000,000	0.35	Silicon Aluminum	7440-21-3 7429-90-5	% of Total Weight 99.10 0.39	0.:
Silicone Resin		mg Total Mass	100.00	140.47	1,000,000	0.35	Silicon Aluminum Titanium	7440-21-3 7429-90-5 7440-32-6	% of Total Weight 99.10 0.39 0.30	0.:
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Silicone Resin	s of package-level information and is no	r mg I otal Mass  t part number specific. This information is considered  ds, including but not limited to RoHS, REACH, and Ch	: 100.00 If to be sufficient	140.47	1,000,000	0.35	Silicon Aluminum Titanium Tungsten Copper	7440-21-3 7429-90-5 7440-32-6 7440-33-7 7440-50-8	% of Total Weight 99.10 0.39 0.30 0.20 0.01	0.3
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